

ABSTRACT OF THE DISCLOSURE

A method of fabricating a surface acoustic wave device includes the steps of: joining a supporting substrate to a second surface of a piezoelectric substrate opposite to a first surface thereof; grinding and polishing the first surface of the piezoelectric substrate; grinding and polishing a third surface of the supporting substrate opposite to another surface thereof to which the second surface of the piezoelectric substrate is joined; and forming, on the first surface of the piezoelectric substrate, an on-chip pattern including comb-like electrodes and electrode pads.